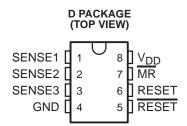
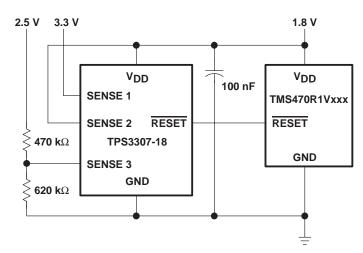
- Qualified for Automotive Applications
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Triple Supervisory Circuits for DSP and Processor-Based Systems
- Power-On Reset Generator with Fixed Delay Time of 200 ms, No External Capacitor Needed

typical applications

Figure 1 lists some of the typical applications for the TPS3307 family, and a schematic diagram for a processor-based system application. This application uses TI part numbers TPS3307–18 and TMS470R1Vxxx.

- Temperature-Compensated Voltage Reference
- Maximum Supply Current of 40 μA
- Supply Voltage Range . . . 2 V to 6 V
- Defined RESET Output from V_{DD} ≥ 1.1 V
- SO-8 Package
- Temperature Range . . . –40°C to 125°C





- Automotive applications using DSPs, Microcontrollers or Microprocessors
- Industrial Equipment
- Programmable Controls
- Automotive Systems

Figure 1. Applications Using the TPS3307-18

description

The TPS3307-18 is a micropower supply voltage supervisor designed for circuit initialization primarily in automotive DSP and processor-based systems, which require more than one supply voltage.

The TPS3307-18 is designed for monitoring three independent supply voltages: 3.3 V/1.8 V/adj,. The adjustable SENSE input allows the monitoring of any supply voltage >1.25 V.

The various supply voltage supervisors are designed to monitor the nominal supply voltage as shown in the following supply voltage monitoring table.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



SGLS136A - NOVEMBER 2002 - REVISED APRIL 2008

description (continued)

SUPPLY VOLTAGE MONITORING

DEVICE	NOMINA	L SUPERVISED	VOLTAGE	THRESHOLD VOLTAGE (TYP)			
DEVICE	SENSE1	SENSE2	SENSE3	SENSE1	SENSE2	SENSE3	
TPS3307-18	3.3 V	1.8 V	User defined	2.93 V	1.68 V	1.25 V [†]	

[†] The actual sense voltage has to be adjusted by an external resistor divider according to the application requirements.

During power-on, RESET is asserted when the supply voltage V_{DD} becomes higher than 1.1 V. Thereafter, the supply voltage supervisor monitors the SENSEn inputs and keeps RESET active as long as SENSEn remain below the threshold voltage V_{IT+}.

An internal timer delays the return of the RESET output to the inactive state (high) to ensure proper system reset. The delay time, $t_{dtyp} = 200$ ms, starts after all SENSEn inputs have risen above the threshold voltage V_{IT+} . When the voltage at any SENSE input drops below the threshold voltage V_{IT}-, the RESET output becomes active (low) again.

The TPS3307-18 incorporates a manual reset input, MR. A low level at MR causes RESET to become active. In addition to the active-low RESET output, the TPS3307-18 includes an active-high RESET output.

The device is available in a standard 8-pin SO package, and is characterized for operation over a temperature range of -40°C to 125°C.

ORDERING INFORMATION[†]

TA	PACKAGE [‡]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	Small Outline (D)	Tape and Reel	TPS3307-18QDRQ1	30718Q

[†] For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

FUNCTION/TRUTH TABLES

MR	SENSE1>VIT1	SENSE2>V _{IT2}	SENSE3>VIT3	RESET	RESET
L	X	X	X	L	Н
Н	0	0	0	L	Н
Н	0	0	1	L	Н
Н	0	1	0	L	Н
Н	0	1	1	L	Н
Н	1	0	0	L	Н
Н	1	0	1	L	Н
Н	1	1	0	L	Н
Н	1	1	1	Н	L

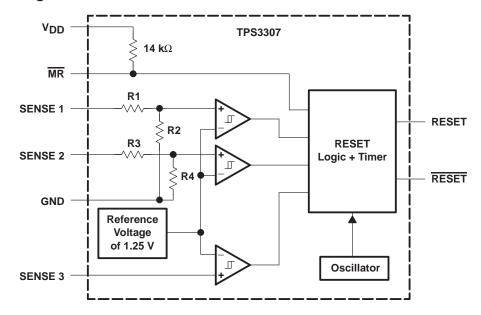
X = Don't care

PowerPAD is a trademark of Texas Instruments Incorporated.

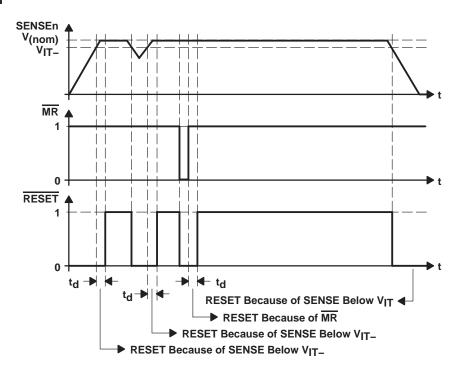


[‡] Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

functional block diagram



timing diagram



SGLS136A - NOVEMBER 2002 - REVISED APRIL 2008

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{DD} (see Note1)	7 V
All other pins (see Note 1)	0.3 V to 7 V
Maximum low output current, I _{OL}	5 mA
Maximum high output current, IOH	–5 mA
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{DD}$)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{DD})	±20 mA
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T _A	–40°C to 125°C
Storage temperature range, T _{stq}	–65°C to 150°C
Soldering temperature	260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

DISSIPATION RATING TABLE

PACKAGE	$T_{\mbox{A}} \le 25^{\circ}\mbox{C}$ POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING	T _A = 125°C POWER RATING
D	725 mW	5.8 mW/°C	464 mW	377 mW	145 mW

recommended operating conditions at specified temperature range

	MIN	MAX	UNIT
Supply voltage, V _{DD}	2	6	V
Input voltage at MR and SENSE3, VI	0	V _{DD} +0.3	V
Input voltage at SENSE1 and SENSE2, VI	0	(V _{DD} +0.3)V _{IT} /1.25V	V
High-level input voltage at MR, VIH	0.7xV _{DD}		V
Low-level input voltage at MR, V _{IL}		0.3×V _{DD}	V
Input transition rise and fall rate at \overline{MR} , $\Delta t/\Delta V$		50	ns/V
Operating free-air temperature range, TA	-40	125	°C



NOTE 1: All voltage values are with respect to GND. For reliable operation the device must not be operated at 7 V for more than t = 1000 h continuously.

TPS3307-18-Q1 TRIPLE PROCESSOR SUPERVISORS

SGLS136A - NOVEMBER 2002 - REVISED APRIL 2008

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER		TEST CON	DITIONS	MIN	TYP	MAX	UNIT		
			$V_{DD} = 2 V \text{ to } 6 V$,	I _{OH} = -20 μA	V _{DD} - 0.2V					
Vон	High-level output voltage		$V_{DD} = 3.3 V$,	$I_{OH} = -2 \text{ mA}$	V _{DD} - 0.4V			V		
			$V_{DD} = 6 V$,	$I_{OH} = -3 \text{ mA}$	V _{DD} - 0.4V					
			$V_{DD} = 2 V \text{ to } 6 V,$	$I_{OL} = 20 \mu A$			0.2			
VOL	V _{OL} Low-level output voltage			I _{OL} = 2 mA			0.4	V		
			V _{DD} = 6 V,	IOL = 3 mA			0.4			
	Power-up reset voltage (see Note 2)		$V_{DD} \ge 1.1 \text{ V},$	I _{OL} = 20 μA			0.4	V		
		VSENSE3			1.2	1.25	1.29	V		
VIT-	Negative-going input threshold voltage (see Note 3)	VSENSE2	$V_{DD} = 2 \text{ V to 6 V},$ $T_{A} = -40^{\circ}\text{C} \text{ to 125}$	50C	1.6	1.68	1.73	V		
	(see Note 3)	VSENSE1	$1A = -40^{\circ}C \cdot 10^{\circ}125$	2.8	2.93	3.02	V			
			V _{IT} _ = 1.25 V		2	10	30			
V _{hys}	Hysteresis at VSENSEn input		V _{IT} _ = 1.68 V	2	15	40	mV			
′			V _{IT} _ = 2.93 V	3	30	60				
		MR	$\overline{MR} = 0.7 \times V_{DD}$	V _{DD} = 6 V		-130	-180			
		SENSE1	VSENSE1 = V _{DD}	= 6 V		5	8			
lН	High-level input current	SENSE2	VSENSE2 = V _{DD}	= 6 V		6	9	μΑ		
		SENSE3	VSENSE3 = V _{DD}		-1		1			
		MR	$\overline{MR} = 0 \text{ V},$	V _{DD} = 6 V		-430	-600			
IL	Low-level input current	SENSEn	VSENSE1,2,3 = 0	V	-1		1	μА		
I _{DD}	Supply current	•					40	μΑ		
Ci	Input capacitance		$V_I = 0 V \text{ to } V_{DD}$			10		pF		



NOTES: 2. The lowest supply voltage at which RESET becomes active. t_r, V_{DD} ≥ 15 μs/V
 3. To ensure best stability of the threshold voltage, a bypass capacitor (ceramic 0.1 μF) should be placed close to the supply terminals.

TPS3307-18-Q1 TRIPLE PROCESSOR SUPERVISORS

SGLS136A - NOVEMBER 2002 - REVISED APRIL 2008

timing requirements at $\rm V_{DD}$ = 2 V to 6 V, $\rm R_{L}$ = 1 M $\Omega,\, C_{L}$ = 50 pF, $\rm T_{A}$ = 25°C

	PARAMET	ER	TEST	CONDITIONS	MIN	TYP	MAX	UNIT
	Dulas width	SENSEn	VSENSEnL = VIT0.2 V,	VSENSEnH = VIT+ +0.2 V	6	10		μs
I _W	Pulse width	MR	$V_{IH} = 0.7 \times V_{DD}$	$V_{IL} = 0.3 \times V_{DD}$	100	150	·	ns

switching characteristics at V_DD = 2 V to 6 V, R $_L$ = 1 M $\Omega,$ C $_L$ = 50 pF, T $_A$ = 25 $^{\circ}$ C

	PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _d	Delay time		$\frac{V_{I(SENSEn)} \ge V_{IT+} + 0.2 \text{ V},}{MR} \ge 0.7 \times V_{DD}$, See timing diagram	140	200	280	ms
t _{PHL}	Propagation (delay) time, high-to-low level output Propagation (delay) time,	MR to RESET MR to RESET MR to RESET	$V_{I(SENSEn)} \ge V_{IT+} + 0.2 \text{ V},$ $V_{IH} = 0.7 \times V_{DD}, V_{IL} = 0.3 \times V_{DD}$		200	600	ns
tPHL	Propagation (delay) time, high-to-low level output	MR to RESET SENSEn to RESET	V _{IH} = V _{IT+} +0.2 V, V _{IL} = V _{IT-} -0.2 V,				
^t PLH	Propagation (delay) time, low-to-high level output	SENSEn to RESET	$MR \ge 0.7 \times V_{DD}$		1	5	μs

TYPICAL CHARACTERISTICS

NORMALIZED SENSE THRESHOLD VOLTAGE

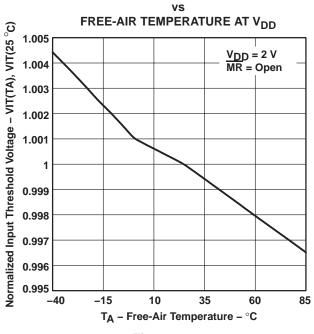
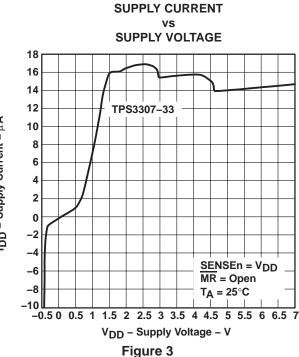


Figure 2

IDD - Supply Current - μA



INPUT CURRENT



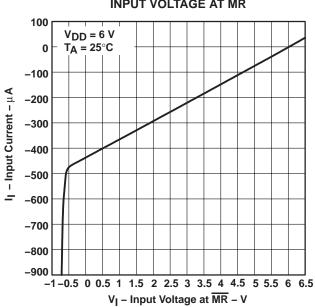


Figure 4

MINIMUM PULSE DURATION AT SENSE

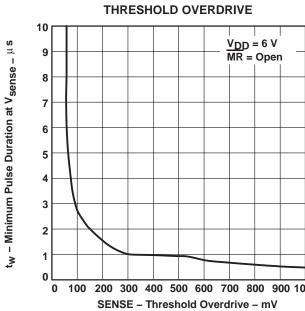
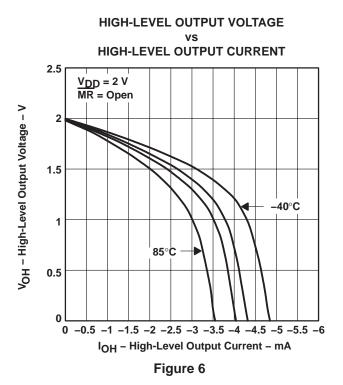
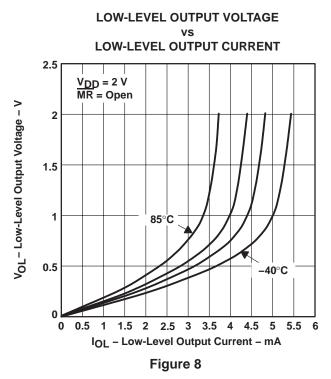
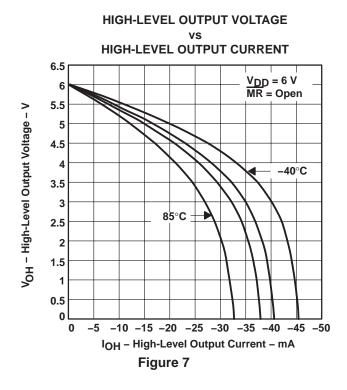


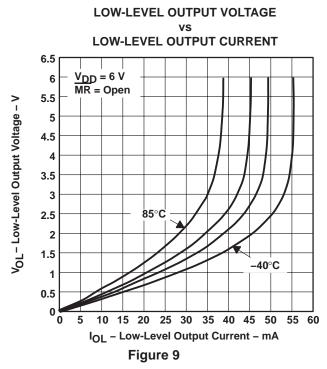
Figure 5

TYPICAL CHARACTERISTICS











PACKAGE OPTION ADDENDUM

6-Feb-2020

PACKAGING INFORMATION

www.ti.com

Orderable Device	Status	Package Type	_	Pins	_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
TPS3307-18QDRG4Q1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 125	30718Q	Samples
TPS3307-18QDRQ1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 125	30718Q	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

6-Feb-2020

OTHER QUALIFIED VERSIONS OF TPS3307-18-Q1:

● Enhanced Product: TPS3307-EP

• Military: TPS3307-18M

NOTE: Qualified Version Definitions:

- Enhanced Product Supports Defense, Aerospace and Medical Applications
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

www.ti.com 5-Jul-2019

TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

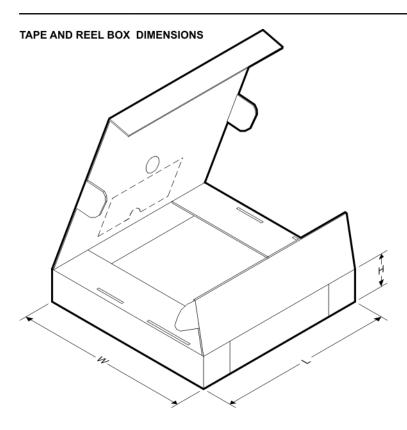
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS3307-18QDRG4Q1	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TPS3307-18QDRQ1	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

www.ti.com 5-Jul-2019



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS3307-18QDRG4Q1	SOIC	D	8	2500	350.0	350.0	43.0
TPS3307-18QDRQ1	SOIC	D	8	2500	350.0	350.0	43.0



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

- 1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
- 4. This dimension does not include interlead flash.
- 5. Reference JEDEC registration MS-012, variation AA.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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